



DEVICE TYPE:				<b>SEMPAC, INC.</b> Open-Pak™ Technologies <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006						
CUSTOMER:			DIE SIZE:							
WIRE TYPE/ SIZE:			NO. OF WIRES:							
THIRD ANGLE PROJECTION UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING	REVISIONS					16 Lead 5.00mm x 5.00mm MLP Open-Pak Bonding Diagram				
	ECN NO.	DATE	DESCRIPTION	APPROVED						
10480	10/21/05	INITIAL RELEASE	D.BENANDO							
DRAWN BY	W. GRIFFITTS	DATE	10/21/05	PACKAGE SIZE:	5.00mm x 5.00mm	SIZE	PART NO.	MLP5X5-16-OP-01	REV	2
APP BY	P. FLASKERUD	DATE	10/21/05	DIE PAD SIZE:	3.10mm x 3.10mm	SCALE	CAD FILE	MLP5X5-16-OP-01-B-R2.DWG	SHEET	1 OF 1